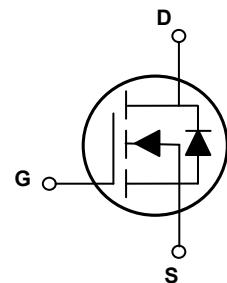
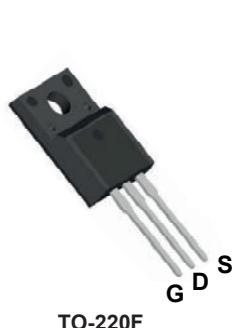


Main Product Characteristics

$V_{(BR)DSS}$	500V
$R_{DS(ON)}$	0.26Ω (Max.)
I_D	20A



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFU20N50 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	500	V
Gate-to-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current, @ Steady-State ($T_C=25^\circ\text{C}$) ¹	I_D	20	A
Continuous Drain Current, @ Steady-State ($T_C=100^\circ\text{C}$)		13	A
Pulsed Drain Current ²	I_{DM}	80	A
Power Dissipation ($T_A=25^\circ\text{C}$)	P_D	72	W
Linear Derating Factor ($T_A=25^\circ\text{C}$)		0.58	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy ³	E_{AS}	1596	mJ
Junction-to-Case	R_{JC}	1.74	$^\circ\text{C}/\text{W}$
Junction-to-Ambient (PCB Mounted, Steady-State) ⁴	R_{JA}	50	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	T_J/T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	500	-	-	V
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=500\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$T_J=125^\circ\text{C}$	-	-	50	
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{GS}}=30\text{V}$	-	-	100	nA
		$V_{\text{GS}}=-30\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	-	0.19	0.26	Ω
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	2.1	3	3.9	V
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$	-	2687	-	pF
Output Capacitance	C_{oss}		-	355	-	
Reverse Transfer Capacitance	C_{rss}		-	10.5	-	
Total Gate Charge	Q_g	$I_D=20\text{A}, V_{\text{DS}}=400\text{V}, V_{\text{GS}}=10\text{V}$	-	49.5	-	nC
Gate-to-Source Charge	Q_{gs}		-	14.3	-	
Gate-to-Drain ("Miller") Charge	Q_{gd}		-	16.4	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=250\text{V}, R_G=10\Omega, I_D=20\text{A}$	-	27.2	-	nS
Rise Time	t_r		-	47.5	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	78.2	-	
Fall Time	t_f		-	41.1	-	
Gate Resistance	R_g	$f=1\text{MHz}$	-	5.6	-	Ω
Source-Drain Ratings and Characteristics						
Continuous Source Current (Body Diode)	I_s	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	20	A
Pulsed Source Current (Body Diode)	I_{SM}	-	-	80	A	
Diode Forward Voltage	V_{SD}	$I_s=20\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.4	V
Reverse Recovery Time	T_{rr}	$T_J=25^\circ\text{C}, I_F=20\text{A}, \text{di}/\text{dt}=100\text{A}/\mu\text{s}$	-	570	-	nS
Reverse Recovery Charge	Q_{rr}		-	5.4	-	μC

Notes:

1. Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. $L=30\text{mH}, I_{\text{AS}}=9.9\text{A}, V_{\text{DD}}=50\text{V}, T_J=25^\circ\text{C}$.
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Typical Electrical and Thermal Characteristic Curves

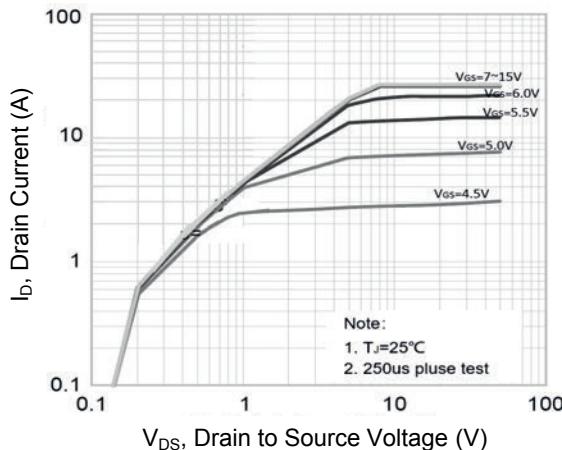


Figure 1. Typical Output Characteristics

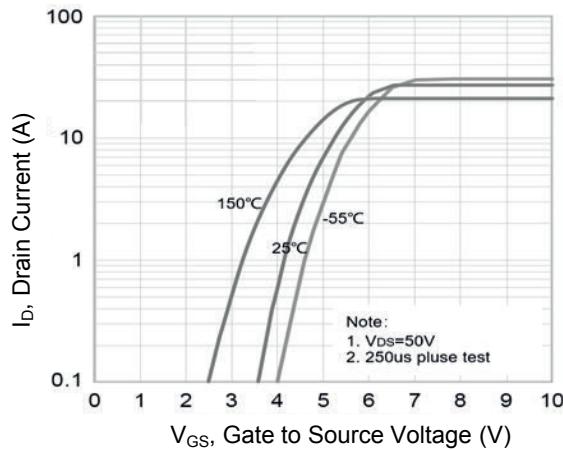


Figure 2. Transfer Characteristics

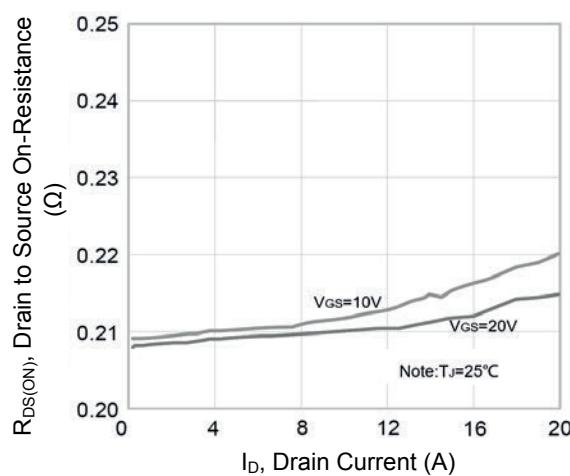


Figure 3. $R_{DS(ON)}$ vs. Drain Current

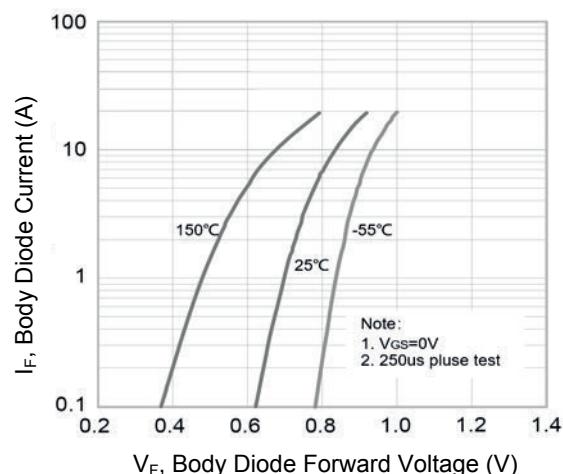


Figure 4. Body Diode Characteristics

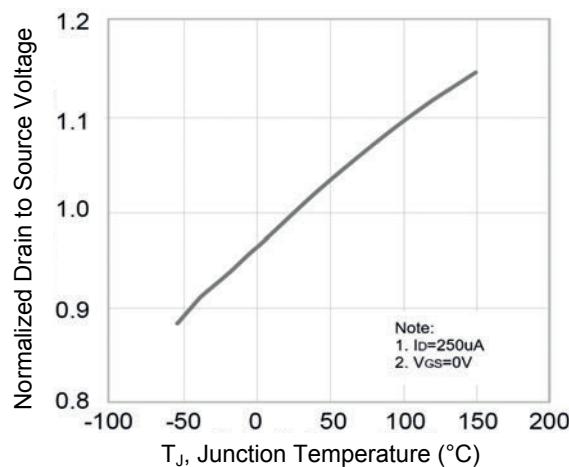


Figure 5. Normalized BV_{DSS} Vs. T_J

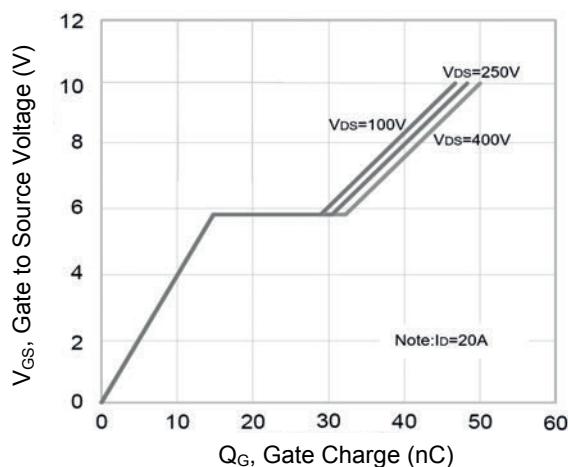


Figure 6. Gate Charge

Typical Electrical and Thermal Characteristic Curves

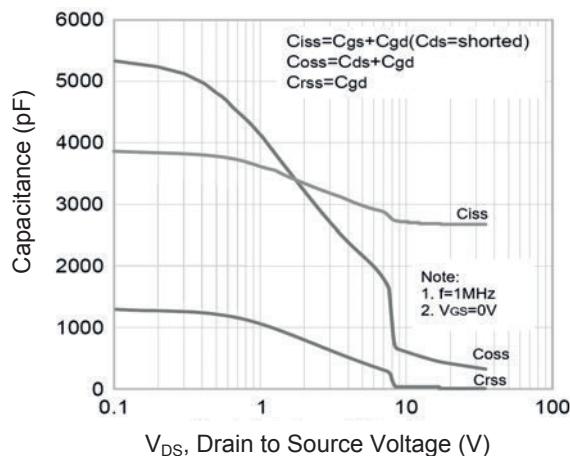


Figure 7. Capacitance Characteristics

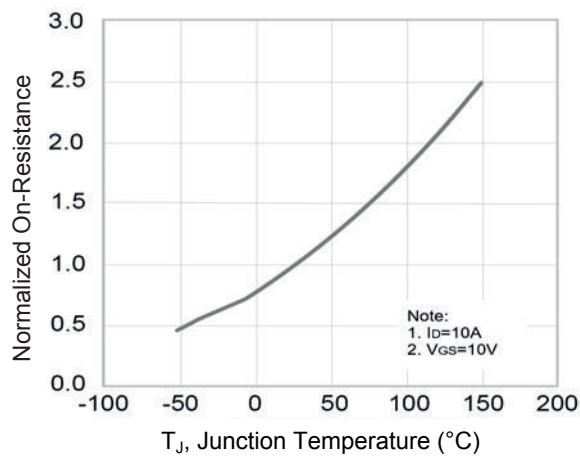


Figure 8. Normalized $R_{DS(ON)}$ vs. T_J

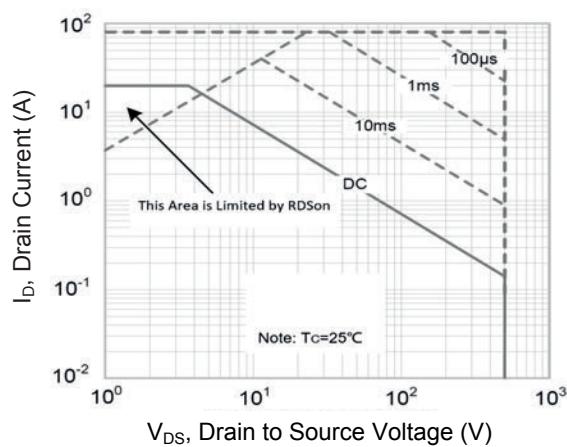
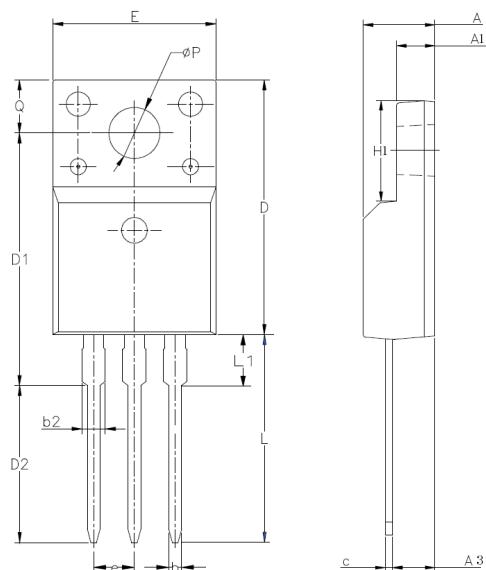


Figure 9. Safe Operation Area

Package Outline Dimensions (TO-220F)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.42	5.02	0.174	0.198
A1	2.30	2.80	0.091	0.110
A3	2.50	3.10	0.098	0.122
b	0.55	0.85	0.020	0.033
b2	-	1.29	-	0.051
c	0.35	0.65	0.014	0.026
D	15.25	16.25	0.600	0.640
D1	13.97	14.97	0.550	0.589
D2	10.58	11.58	0.417	0.456
E	9.73	10.36	0.383	0.408
e	2.54 BCS		0.10 BCS	
H1	6.40	7.00	0.252	0.276
L	12.48	13.48	0.491	0.531
L1	-	2.00	-	0.079
ΦP	3.00	3.40	0.118	0.134
Q	3.05	3.55	0.120	0.140

Order Information

Device	Package	Marking	Carrier	Quantity
GSFU20N50	TO-220F	U20N50	Tape & Reel	50pcs / Tube